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Heydari(10) **Pub. No.: US 2022/0354017 A1**(43) **Pub. Date: Nov. 3, 2022**(54) **INTELLIGENT POD-BASED COOLING
LOOP WITH DRY COOLER FOR MOBILE
DATACENTER COOLING SYSTEMS**(71) Applicant: **Nvidia Corporation**, Santa Clara, CA
(US)(72) Inventor: **Ali Heydari**, Albany, CA (US)(21) Appl. No.: **17/246,330**(22) Filed: **Apr. 30, 2021****Publication Classification**(51) **Int. Cl.**
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7/20281 (2013.01); **H05K 7/20745** (2013.01)(57) **ABSTRACT**

Systems and methods for cooling a mobile datacenter are disclosed. In at least one embodiment, a cooling loop is located on a mobile unit and includes at least one cold plate within a pod on a mobile unit and includes a dry cooler external to a pod on a mobile unit so as to enable coolant to be provided to a cold plate and to enable such coolant to be provided to a dry cooler for removal of heat from at least one computing device to an ambient environment.

